

Amendments to the Claims:

Please add new claims 23-35.

This listing of claims replaces all prior versions, and listings, of claims in the application.

Listing of claims:

1. (original) A head for polishing a wafer, comprising:
 - a carrier;
 - a retainer ring disposed on a lower edge of said carrier;
 - a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
 - a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes.
2. (original) The apparatus according to claim 1, wherein an edge of said surface portion of said supporter is chamfered.
3. (original) The apparatus according to claim 1, wherein an edge of said surface portion of said supporter is rounded.
4. (original) The apparatus according to claim 1, wherein said first chamber has a fluid passage communicating external to said polishing head.
5. (original) The apparatus according to claim 1, wherein said second chamber has a fluid passage communicating external to said polishing head.

6. (original) The apparatus according to claim 1, wherein films are adhered on said flat surface around said first holes, each of said films sized to fit within said third holes.
7. (original) The apparatus according to claim 1, wherein each of said films has a thickness less than that of said membrane.
8. (original) The apparatus according to claim 1, wherein at least one of said second holes penetrates a center portion of said supporter, and for the at least one of said second holes, there is no corresponding hole formed in said membrane.
9. (original) An apparatus for polishing a wafer comprising:
 - a carrier;
 - at least one membrane dividing said carrier to form at least two chambers;
 - a retainer ring disposed on an edge of said polishing head; and
 - a chucking ring disposed on a lower portion of said polishing head.
10. (original) The apparatus according to claim 9,
 - wherein said polishing head further includes a center supporter disposed in said carrier to provide a first chamber, and a middle supporter disposed in said carrier on the same plane as that of the center supporter, to provide a second chamber;
 - wherein said membrane is composed of first and second membranes enclosing said center and middle supporters separable from surface portions of said supporters; and
 - wherein said chucking ring is disposed in said carrier to provide a third chamber.
11. (original) The apparatus according to claim 10, wherein a plurality of first holes are formed in said surface portion of said center supporter to communicate with said first chamber, a plurality of second holes are formed in said surface portion of said middle supporter to communicate with said second chamber, and a plurality of third holes are formed in said chucking ring to communicate with said third chamber.

12. (original) The apparatus according to claim 10, wherein said chucking ring is disposed between said center supporter and said middle supporter.
13. (original) The apparatus according to claim 10, wherein said chucking ring is disposed between said middle supporter and an inner surface of said carrier.
14. (original) The apparatus according to claim 10, wherein said first, second and third chambers have respective first, second and third fluid passages communicating externally to said polishing head.
15. (original) The apparatus according to claim 10, wherein said middle supporter is composed of a ring shape.
16. (original) The apparatus according to claim 15, wherein said second membrane is composed of a ring shape corresponding to said middle supporter.
17. (original) The apparatus according to claim 9, wherein films are adhered on said chucking ring around said third holes to operate as a medium in chucking and releasing of said wafer.
18. (original) The apparatus according to claim 10, wherein edges of said surface portions of said center and middle supporters are rounded or chamfered.
19. (original) An apparatus for polishing a wafer comprising:
 - a supporting portion having an abrasive pad disposed thereon;
 - a polishing head disposed over said abrasive pad; and
 - said polishing head comprising:
 - a carrier;
 - at least one membrane dividing said carrier to form at least two chambers;

a retainer ring disposed on an edge of said polishing head; and
a chucking ring disposed on a lower portion of said polishing head.

20. (original) The apparatus according to claim 19, wherein said chucking ring is located between a center supporter and a middle supporter disposed in the carrier.
21. (original) The apparatus according to claim 19, wherein said chucking ring is located between a center supporter and a middle supporter disposed in the carrier between a middle supporter and an inner surface of the carrier.
22. (original) An apparatus for polishing a wafer, comprising:
a supporting portion having an abrasive pad disposed thereon;
a polishing head disposed over said abrasive pad; and
said polishing head comprising:
a carrier;
a retainer ring disposed on a lower edge of said carrier;
a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes.

23. (new) A head for polishing a wafer, comprising:
- a carrier having a cavity and a lower edge;
 - a retainer ring disposed at the lower edge of the carrier;
 - a supporter disposed in the cavity of the carrier and configured to provide a first fluid path, the supporter having an outer surface including a plurality of first holes which communicate with the first fluid path; and
 - a membrane enclosing the outer surface of the supporter and having a like plurality of second holes in alignment with the first holes of the supporter, said membrane being spaced apart from the outer surface of the supporter in a first position and abutting the outer surface of the supporter in a second position.
24. (new) The head of claim 23 wherein the first fluid path of the supporter comprises a fluid chamber located in the supporter.
25. (new) The head of claim 23 wherein the second holes of the membrane form a seal about the corresponding first holes of the supporter when the membrane is in the second position.
26. (new) The head of claim 23 further comprising a plurality of film structures, each film structure disposed on the outer surface of the supporter about one of each of the first holes.
27. (new) The head of claim 27, wherein the film structures mate with the second holes of the membrane such that the film structures fit inside the second holes.
28. (new) The head of claim 27, wherein the film structures have a thickness that is less than a thickness of the membrane.
29. (new) The head of claim 23 further comprising a plurality of third holes formed through

the outer surface of the supporter, the plurality of third holes communicating with a second fluid path formed in the supporter.

29. (new) The head of claim 29 wherein the plurality of third holes communicate with an interior region of the membrane between the membrane and the outer surface of the supporter when the membrane is in the second position.
30. (new) The head of claim 23 wherein an edge of the surface portion of the supporter is chamfered.
31. (new) A method for polishing a wafer, comprising the steps of:
 - vacuum-absorbing a wafer through a vacuum hole of a membrane positioned under a polishing head;
 - locating the vacuum-absorbed wafer on a polishing pad; and
 - polishing the wafer.
32. (new) The method of claim 31 wherein vacuum-absorbing comprises drawing a vacuum on a fluid path formed through a supporter of the polishing head on which the membrane is mounted.
33. (new) The method of claim 32 wherein the vacuum hole of the membrane comprises multiple first vacuum holes and wherein the supporter includes multiple second vacuum holes in alignment with the multiple first vacuum holes, and wherein the fluid path is in communication with the multiple second vacuum holes.
34. (new) The method of claim 33 wherein, during vacuum absorbing, each of the first vacuum holes forms a seal about the corresponding second vacuum hole.
35. (new) The method of claim 33 wherein a plurality of film structures are disposed on an

outer surface of the supporter about each of the multiple second holes, each of the films mating with the corresponding first vacuum hole formed in the membrane.